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Version with markings to show changes. (Because changes were made only to pages i-iv, 1, and 381, only these pages are included below.)

ELECTRICAL CONTACT STRUCTURES FORMED BY CONFIGURING A FLEXIBLE WIRE TO HAVE A SPRINGABLE SHAPE AND OVERCOATING THE WIRE WITH AT LEAST ONE LAYER OF A RESILIENT CONDUCTIVE MATERIAL, METHODS OF MOUNTING THE CONTACT STRUCTURES TO ELECTRONIC COMPONENTS, AND APPLICATIONS FOR EMPLOYING THE CONTACT STRUCTURES



## OUTLINE

<u>TOPIC HEADING</u>	<u>pg. #</u>
TECHNICAL FIELD OF THE INVENTION .....	1
CROSS-REFERENC TO RELATED APPLICATIONS .....	[2] 1
BACKGROUND OF THE INVENTION .....	[4] 1
DISCLOSURE (SUMMARY) OF THE INVENTION .....	[23] 24
BRIEF DESCRIPTION OF THE DRAWINGS .....	[29] 31
DETAILED DESCRIPTION OF THE INVENTION .....	[47] 50
Discussion of parent case 08/152,812 .....	[47] 50
Discussion of parent case 08/340,144 .....	[53] 57
BONDING A WIRE TO AN AREA ON A SUBSTRATE .....	[57] 61
Figures 1, 1A-1F	
PROPERTIES OF THE WIRE .....	[61] 65
FORMING AND SHAPING OF THE WIRE STEM .....	[64] 68
Figures 2, 2A-2H	
TYPES OF WIREBONDERS .....	[82] 87
ULTRASONIC FORMING .....	[84] 89
COMPENSATING FOR SPRINGBACK OF THE WIRE .....	[87] 92
Figures 3A and 3B	
SEVERING THE WIRE .....	[91] 96
Figures 4A-4D	

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COATING THE WIRE STEM .....	[98]
Figures 5, 5A-5I	<u>104</u>
COATING TECHNIQUES, MATERIALS AND THICKNESSES .....	[109]
	<u>115</u>
CHARACTERISTICS OF THE CONTACT AREA .....	[119]
	<u>126</u>
SELF-PLANARIZING FEATURES .....	[123]
Figures 6A-6C	<u>130</u>
ELECTRONIC COMPONENTS .....	[129]
	<u>136</u>
SEMICONDUCTOR PACKAGES .....	[130]
Figures 7A-7D	<u>137</u>
SACRIFICIAL ELEMENTS .....	[135]
Figures 8A-8D	<u>142</u>
SACRIFICIAL MEMBERS AND PROBE EMBODIMENTS .....	[137]
Figures 9A-9C	<u>144</u>
ADDITIONAL PROBE EMBODIMENTS .....	[141]
Figures 10A-10K	<u>148</u>
CONTACT-FABRICATION ON A SACRIFIAL SUBSTRATE .....	[147]
Figures 11A-11F	<u>155</u>
CONTACT GANG TRANSFER .....	[150]
Figures 12A-12F	<u>158</u>
TEMPORARY/PERMANENT METHODOLOGY .....	[158]
Figures 13A-13B	<u>166</u>
CHIP-LEVEL MOUNTING PROCESS .....	[163]
Figures 14A-14E	<u>171</u>
WAFER-LEVEL MOUNTING RESILIENT CONTACT STRUCTURES .....	[170]
Figures 14F-14G, 15, 15A	<u>178</u>
NO SHORTING LAYER REQUIRED .....	[176]
Figures 16A-16D	<u>185</u>
Figures 16E-16F (stacking chips)	

INTERPOSERS .....	[181]
Figures 17A-17E .....	<u>190</u>
ADDITIONAL INTERPOSER EMBODIMENTS .....	[188]
Figures 18A/B, 19A/B, 20A/B, 21, 221/B, 22C, 22D-22F .....	<u>197</u>
ADDITIONAL SEMICONDUCTOR PACKAGE EMBODIMENTS .....	[204]
Figures 23A, 23B, 23C .....	<u>215</u>
"LOOP" EMBODIMENTS .....	[209]
Figures 24A, 24B .....	<u>220</u>
THERMAL PATH EMBODIMENTS .....	[214]
Figures 24C/D, 24E .....	<u>225</u>
ASSEMBLIES OF ELECTRONIC COMPONENTS .....	[217]
Figures 25-30 .....	<u>228</u>
ASSEMBLIES INCLUDING ELECTRONIC DEVICES .....	[236]
Figures 31, 32 .....	<u>248</u>
CARRIER ASSEMBLIES .....	[240]
Figures 33-35, 36A/B/C, 37, 38-38A, .....	<u>253</u>
DUT TEST INTERFACE ARRANGEMENT .....	[255]
Figures 39 .....	<u>269</u>
VARIOUS ADDITIONAL EMBODIMENTS .....	[257]
NON-CONDUCTIVE STEM .....	<u>272</u>
Figures 40A, 40B .....	[257]
Figures 40A, 40B .....	<u>272</u>
STEM AFFIXED WITHOUT BONDING .....	[259]
Figures 41A-41C .....	<u>274</u>
MANUALLY SHAPING THE WIRE STEM .....	[260]
Figures 42, 42A/B, 42C .....	<u>275</u>
OVERCOMING STICTION AND PRE-CLEANING THE WIRE .....	[263]
Figures 43A, 43B .....	<u>278</u>
ORIENTATION OF THE CONTACT STRUCTURES .....	[264]
Figures 44 .....	<u>280</u>

03746960-01001

FLEXURE MECHANISMS .....	[266]
Figures 45 .....	<u>282</u>
REDUCING INDUCTANCE .....	[267]
Figures 46A-46F, 46G .....	<u>283</u>
TAPERED WIRE STEM .....	[270]
Figure 47 .....	<u>286</u>
REMOVING THE WIRE STEM .....	[271]
Figures 48A-48E .....	<u>286</u>
EUTECTIC CONTACT TIP .....	[272]
Figures 49A-49C .....	<u>287</u>
TOPGRAPHICAL CONTACT TIPS .....	[274]
Figures 50A, 50B .....	<u>290</u>
DEMI-COATING .....	[275]
Figures 51A-51C .....	<u>292</u>
CONTACTING A CENTRAL PORTION OF THE WIRE STEM .....	[276]
Figures 52A-52D .....	<u>293</u>
MULTIPLE FREE-STANDING WIRE STEMS, SINGLE SEVERING STEP .....	[278] <u>294</u>
Figures 52E-52F, 53A-53D .....	
FLAT TAB TIPS, AND METHODS OF MAKING INTERCONNECTIONS .....	[282] <u>299</u>
Figures 54 .....	
ADVANTAGES .....	[284] <u>301</u>
CLAIMS .....	[290] <u>308</u>
ABSTRACT .....	[356] <u>381</u>

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## TITLE

ELECTRICAL CONTACT STRUCTURES FORMED BY CONFIGURING A FLEXIBLE WIRE TO HAVE A SPRINGABLE SHAPE AND OVERCOATING THE WIRE WITH AT LEAST ONE LAYER OF A RESILIENT CONDUCTIVE MATERIAL, METHODS OF MOUNTING THE CONTACT STRUCTURES TO ELECTRONIC COMPONENTS, AND APPLICATIONS FOR EMPLOYING THE CONTACT STRUCTURES

## TECHNICAL FIELD OF THE INVENTION

[0001] The invention relates to contact structures for making electrical connections to, from and between electronic components, especially microelectronic components and, more particularly, to contact structures exhibiting resiliency and/or compliance.

## ABSTRACT

Contact structures exhibiting resilience or compliance for a variety of electronic components are formed by bonding a free end of a wire to a substrate, configuring the wire into a wire stem having a springable shape, severing the wire stem, and overcoating the wire stem with at least one layer of a material chosen primarily for its structural (resiliency, compliance) characteristics. [A variety of techniques for configuring, severing, and overcoating the wire stem are disclosed. In an exemplary embodiment, a free end of a wire stem is bonded to a contact area on a substrate, the wire stem is configured to have a springable shape, the wire stem is severed to be free-standing by an electrical discharge, and the free-standing wire stem is overcoated by plating. A variety of materials for the wire stem (which serves as a falsework) and for the overcoat (which serves as a superstructure over the falsework) are disclosed. Various techniques are described for mounting the contact structures to a variety of electronic components (e.g., semiconductor wafers and dies, semiconductor packages, interposers, interconnect substrates, etc.), and various process sequences are described. The resilient contact structures described herein are ideal for making a "temporary" (probe) connections to an electronic component such as a semiconductor die, for burn-in and functional testing. The self-same resilient contact structures can be used for subsequent permanent mounting of the electronic component, such as by soldering to a printed circuit board (PCB). An irregular topography can be created on or imparted to the tip of the contact structure to enhance its ability to interconnect resiliently with another electronic component. Among the numerous advantages of the present invention is the great facility with which the tips of a plurality of contact structures can be made to be coplanar with one another. Other techniques and embodiments, such as wherein the falsework wirestem protrudes beyond an end of the superstructure, or is melted down, and wherein multiple free-standing resilient contact structures can be fabricated from loops, are described.]

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Abstract  
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